



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

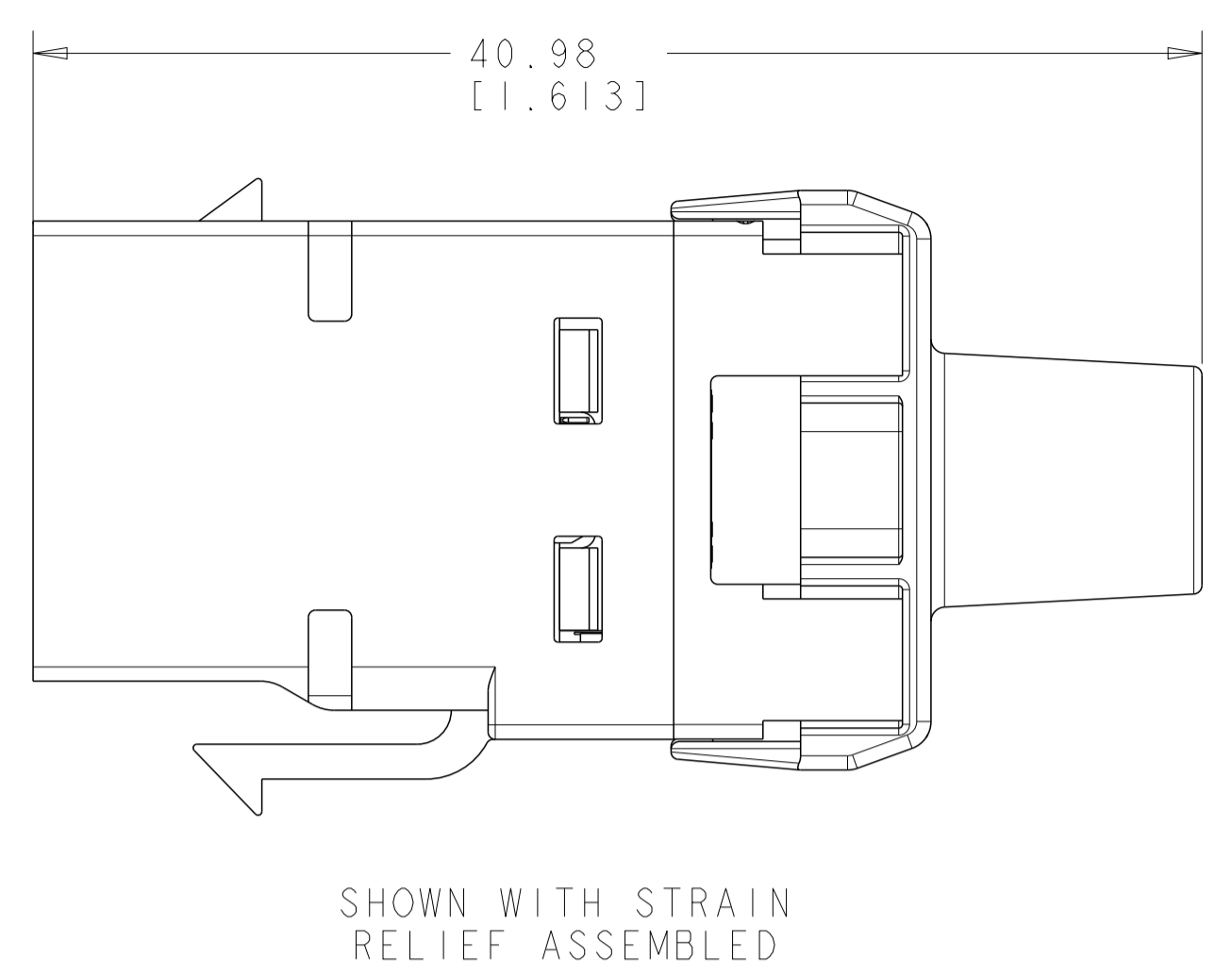
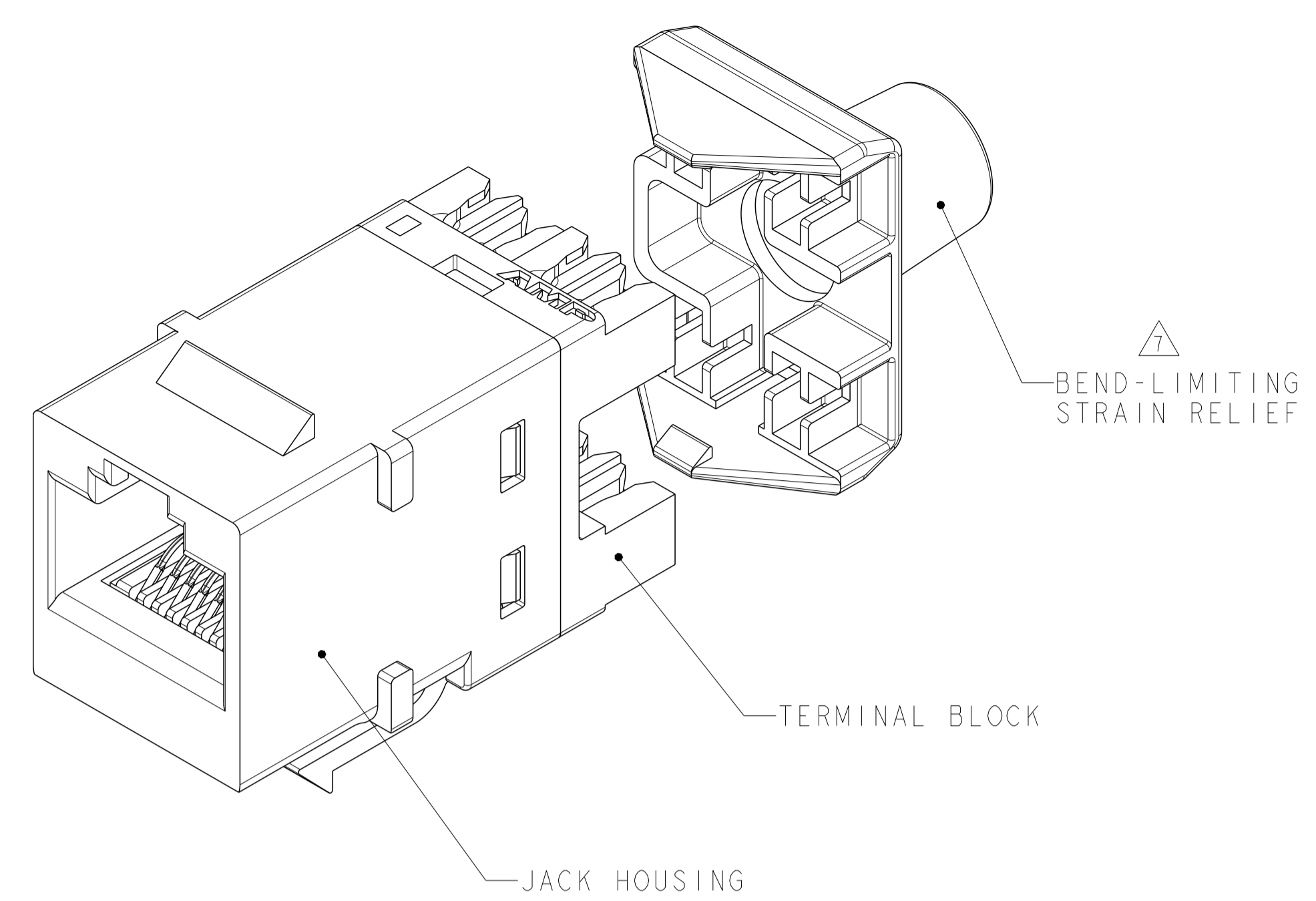
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

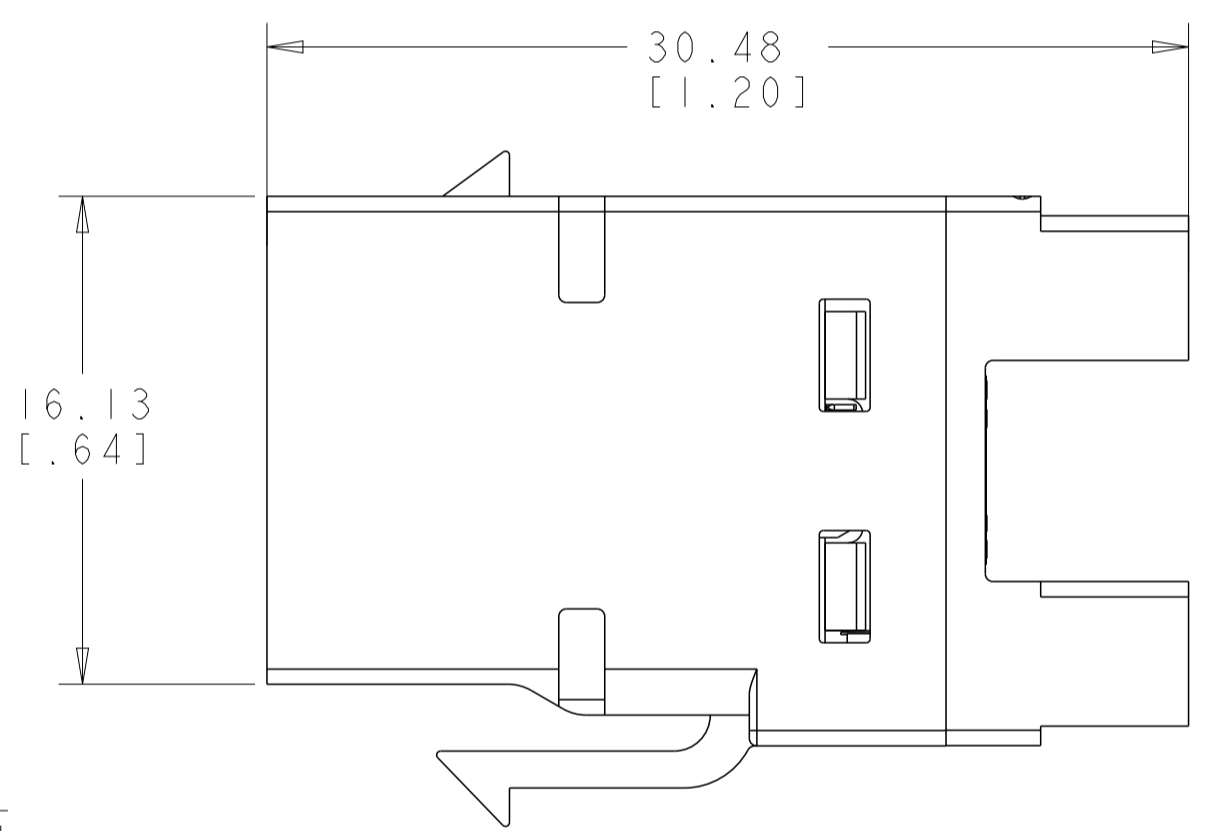
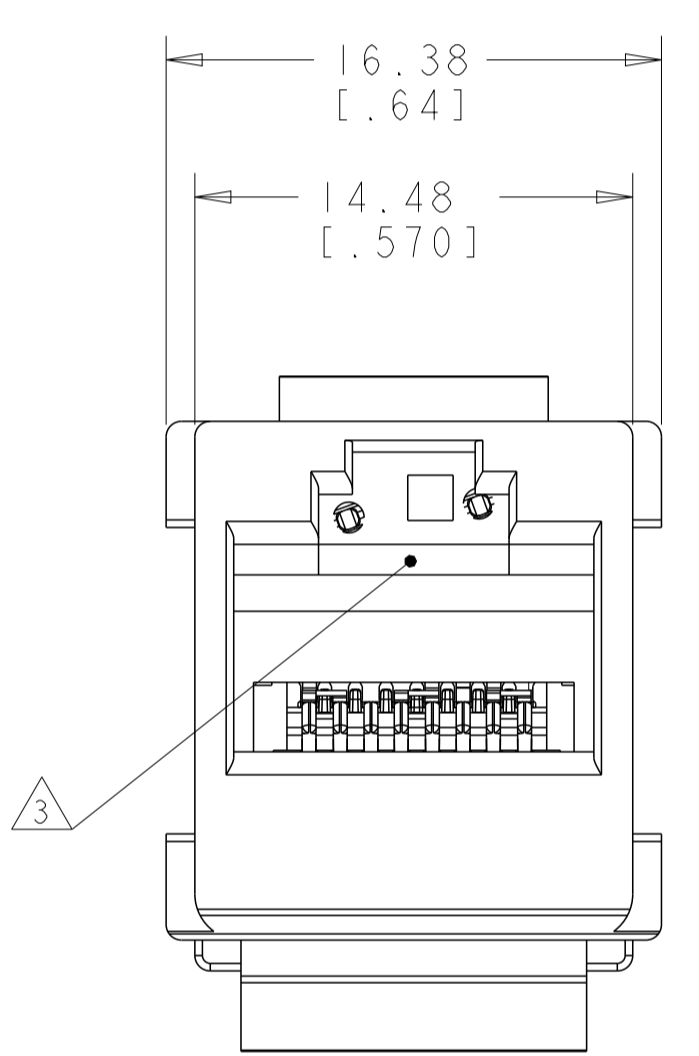
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



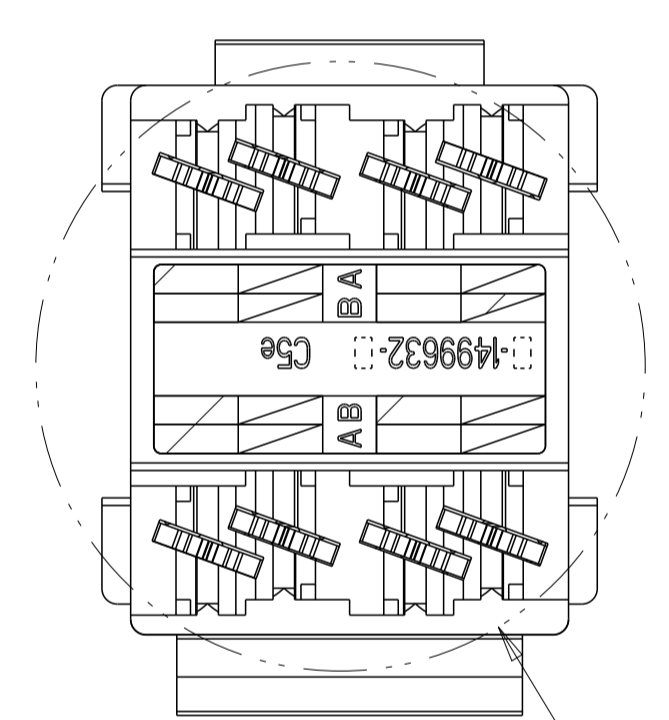
LOC		DIST		REVISIONS			
P	LTN	DESCRIPTION	DATE	OWN	APVD		
E		REV ECO-10-008894	28APR2010	LH	SA		
F		REV ECO-11-008739	27APR2011	LH	SA		
F1		REV: ECO-15-000709	20JAN2015	GG	LS		



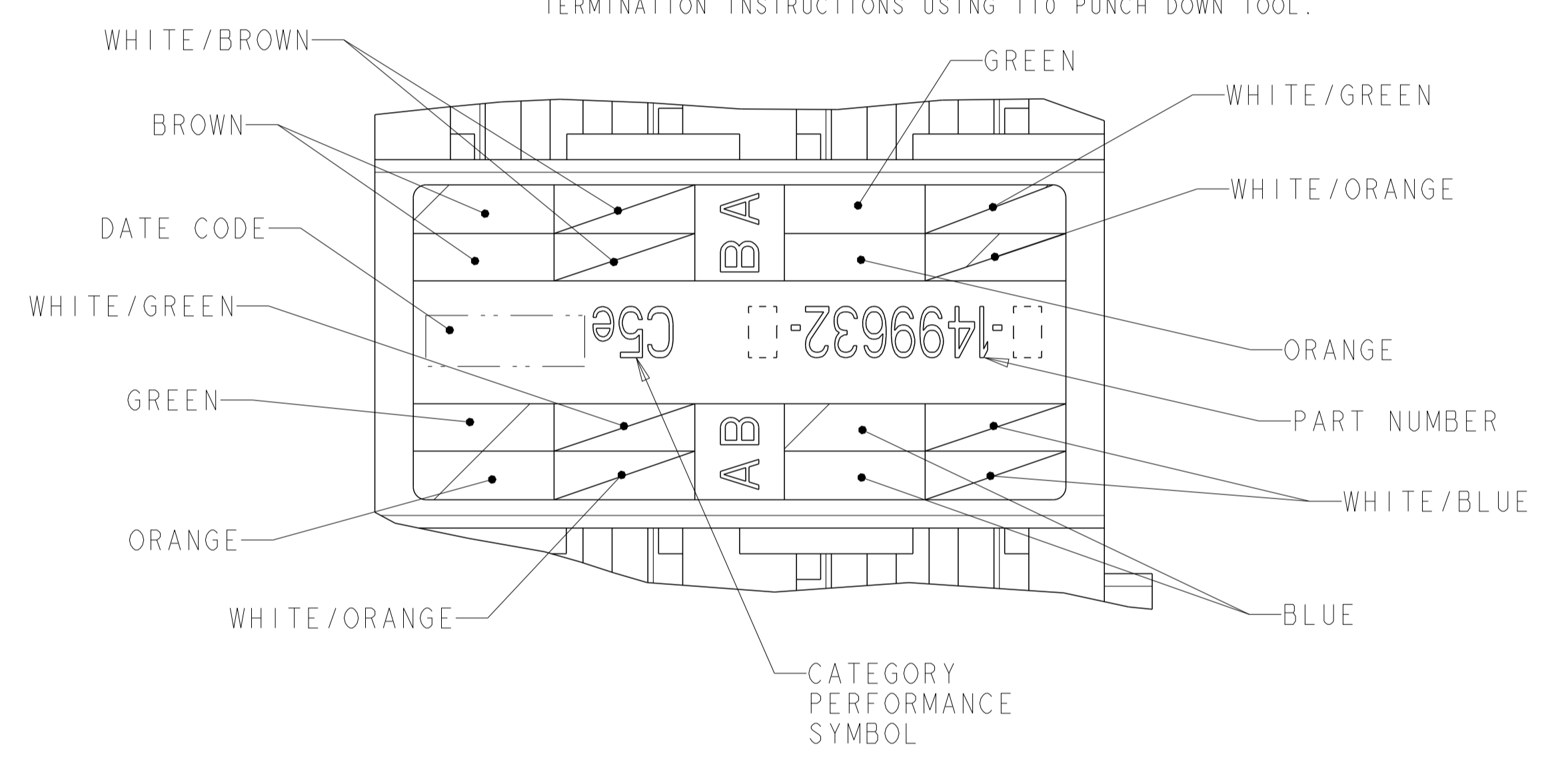
- △ MATERIAL: JACK HOUSING - POLYCARBONATE, 94V-0 RATED. 110 BLOCK AND STRAIN RELIEF - POLYCARBONATE. ARRAY TRAY - PBT POLYESTER. JACK CONTACTS ARRAY - BERYLLIUM COPPER, PLATED WITH 1.27µm [.000050] MINIMUM THICK GOLD IN LOCALIZED AREA AND 3.81µm [.000150] MINIMUM THICK MATTE TIN IN BOARD INTERFACE AREA OVER 1.27µm [.000050] MINIMUM THICK NICKEL UNDERPLATE.
- 2. KL 110 JACK WILL TERMINATE 22-24 AWG SOLID AND 24-26 AWG STRANDED CONDUCTORS, 1.27[.050] MAXIMUM INSULATION DIAMETER. JACK WILL ACCEPT CONDUCTORS UP TO 1.45 [.057] BUT REQUIRE THE USE OF A STRAIN RELIEF.
- △ CAVITY CONFORMS TO FCC RULES AND REGULATIONS) PART 68 SUBPART F REQUIREMENTS.
- 4. MOUNTING PANEL THICKNESS 1.22 - 1.55 [.048 - .061].
- △ THESE TWO SUGGESTED CUTOUT OPENINGS ARE USED IN TANDEM WITH DUAL FRONT AND BACK CUTOUTS.
- △ ONE MODULAR JACK ASSEMBLY AND ONE STRAIN RELIEF PER POLYBAG.
- △ USE OF STRAIN RELIEF IS OPTIONAL.
- △ REFER TO 408-8858 FOR TERMINATION INSTRUCTIONS USING SL SERIES TOOL TERMINATION. REFER TO 408-8417 FOR TERMINATION INSTRUCTIONS USING 110 PUNCH DOWN TOOL.



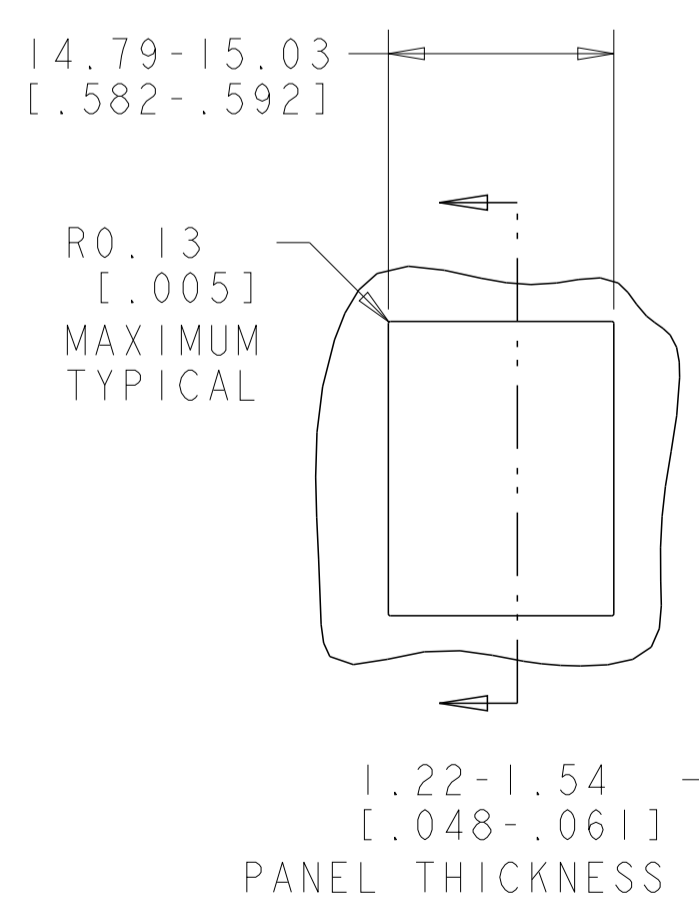
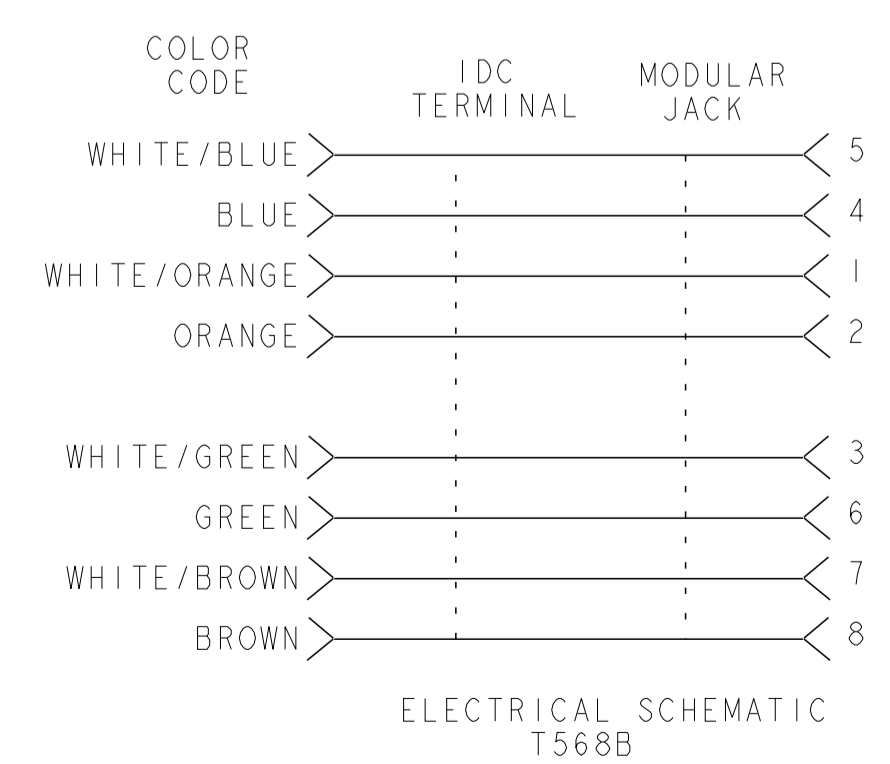
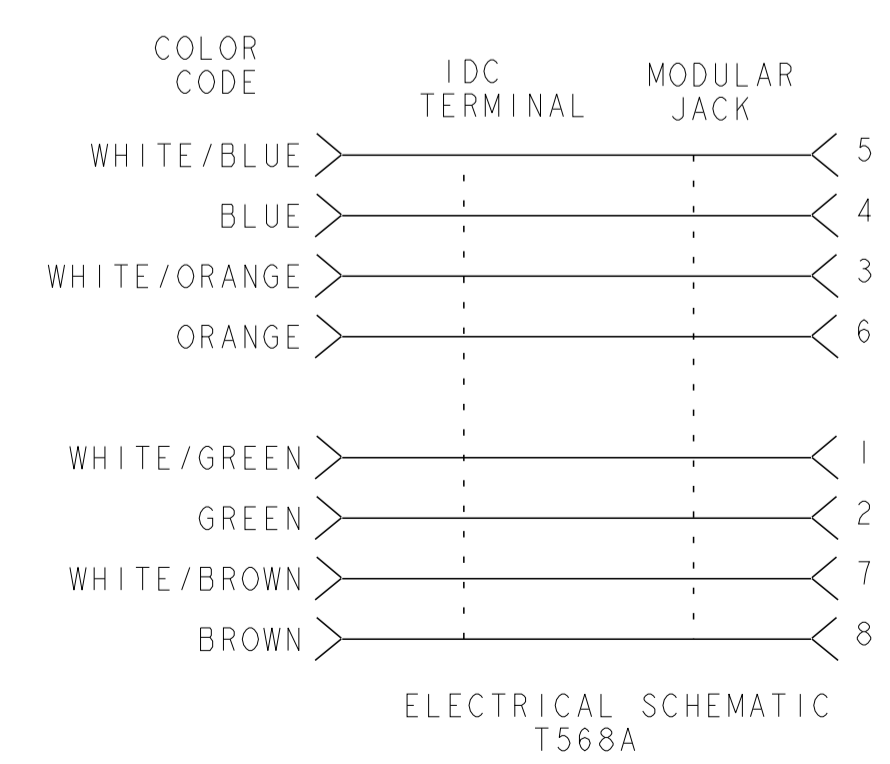
TERMINAL NUMBER 1



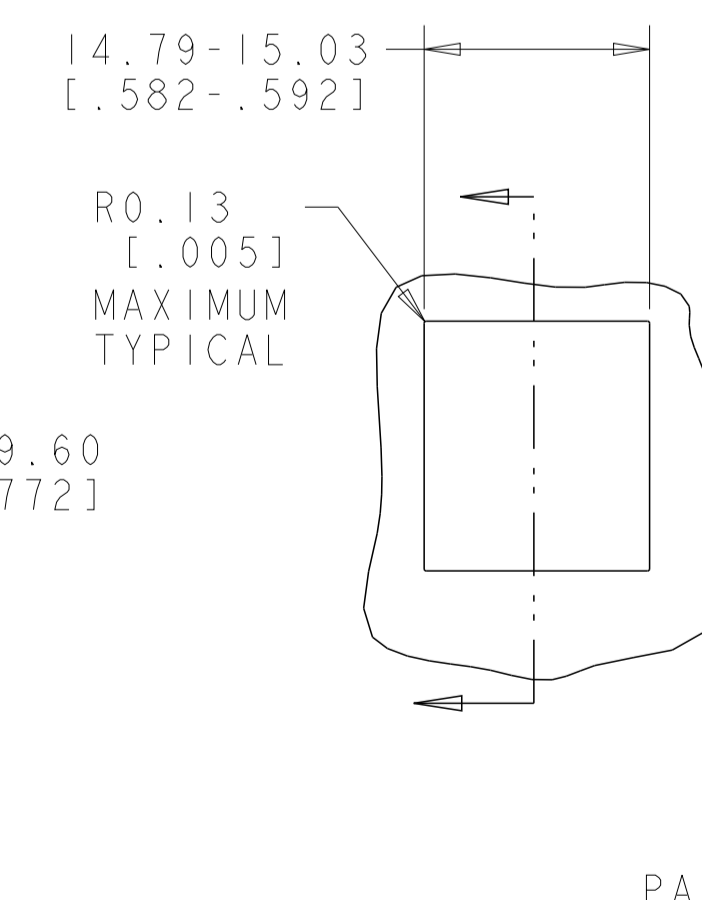
SEE DETAIL A



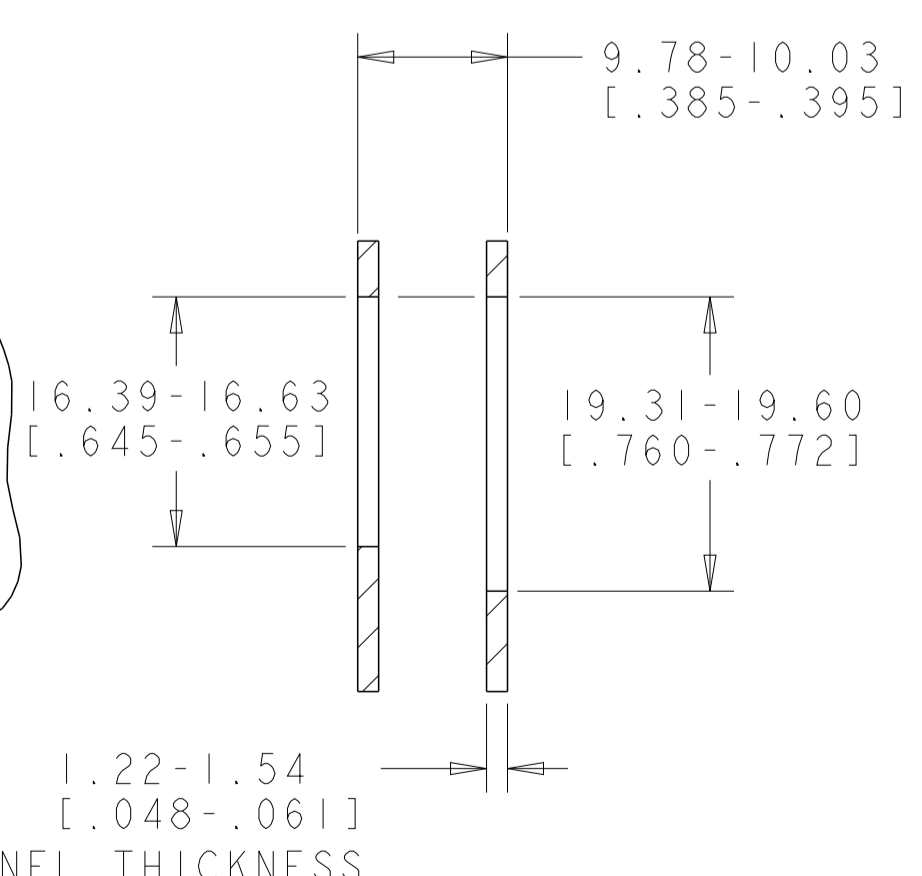
DETAIL A SCALE 10:1



SINGLE PANEL CUTOUT



SUGGESTED FLUSH MOUNT PANEL APPLICATION CUTOUT



HOUSING COLOR	PART NUMBER
ALPINE WHITE	1-1499632-3
ELECTRIC IVORY	1-1499632-1
VIOLET	1-1499632-0
GREEN	1499632-9
YELLOW	1499632-8
RED	1499632-7
BLUE	1499632-6
ORANGE	1499632-5
NEMA GRAY	1499632-4
WHITE	1499632-3
BLACK	1499632-2
LIGHT ALMOND	1499632-1

THIS DRAWING IS A CONTROLLED DOCUMENT.

OWN: L. SMITH 01JUL2005
CHK: C. DOOLEY 06JUL2005
APVD: C. DOOLEY 06JUL2005

TE Connectivity

ASSY, CAT 5E, UTP, KL SERIES JACK

SIZE: A100779 C=1499632

Customer Drawing

SCALE: 4:1 SHEET 1 OF 1 REV F1